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## MAX98371

# Digital Input Class D Speaker Amplifier with Dynamic Headroom Tracking

### General Description

The MAX98371 is a high-efficiency, mono Class D audio amplifier featuring dynamic headroom tracking (DHT). DHT automatically optimizes the headroom available to the Class D amplifier as the power supply voltage varies, due to sudden transients and declining battery life to maintain a consistent listening experience. A wide 5.5V to 18V supply range allows the device to reach 19W into an 8Ω load.

The MAX98371's flexible digital audio interface (DAI) supports I<sup>2</sup>S, left-justified, and TDM formats. The digital audio interface accepts 32kHz, 44.1kHz, 48kHz, 88.2kHz, and 96kHz sample rates with 16-/24-/32-bit data supported for all data formats. In TDM mode, the device can support up to 16 channels of audio data. A unique clocking structure eliminates the need for an external MCLK signal that is typically needed for PCM communication. This reduces pin count and simplifies board layout.

Active emissions limiting with edge rate control minimizes EMI, and eliminates the need for output filtering found in traditional Class D devices.

An 8-bit PVDD supply voltage ADC enables the Dynamic Headroom Tracking circuit. DHT optimizes audio program peak behavior as the supply voltage varies and provides flexible user-defined parameters.

Thermal foldback protection ensures robust behavior when the thermal limits of the device are exercised. The circuit can be enabled to automatically reduce the output power above a user specified temperature. This allows for uninterrupted music playback even at high ambient temperatures. Traditional thermal protection is also available in addition to robust overcurrent protection.

All MAX98371 control is performed using a standard 2-wire, I<sup>2</sup>C interface. One of sixteen slave addresses can be selected through two, four-level address pins. The IC is available in a 0.4mm pitch, 30-bump WLP package. It is specified over the extended, -40°C to +85°C temperature range.

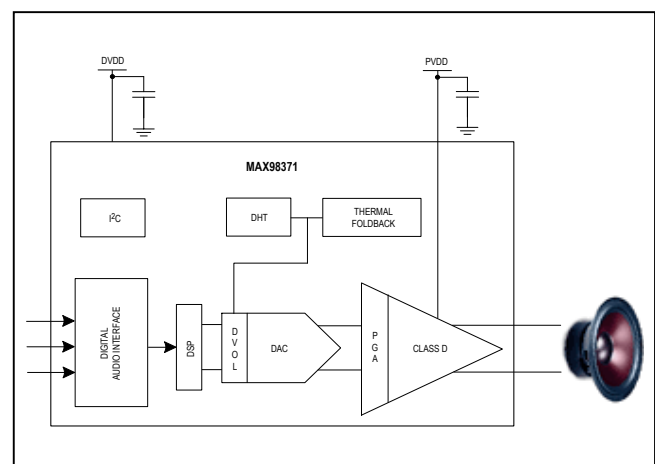
### Applications

- Tablets
- Notebook Computers
- Soundbars

### Benefits and Features

- Wide Supply Range (5.5V to 18V)
- Dynamic Headroom Tracking Maintains a Consistent Listening Experience
- Integrated Thermal Foldback Allows Robust Operation in a WLP Package
- Remote Output Sensing Allows Up to 20dB THD+N Improvement When Ferrites Are Used
- Class D Edge Rate Control Enables Filterless Operation
- 110dB A-Weighted Dynamic Range
- Output Power at 1% THD+N:
  - 15.7W into 8Ω, V<sub>PVDD</sub> = 17V
  - 13.2W into 4Ω, V<sub>PVDD</sub> = 12V
- Output Power at 10% THD+N:
  - 19W into 8Ω, V<sub>PVDD</sub> = 17V
  - 15.8W into 4Ω, V<sub>PVDD</sub> = 12V
- Speaker Amplifier Efficiency
  - 91% at 10W into 8Ω, V<sub>PVDD</sub> = 12V
  - 81% at 15W into 4Ω, V<sub>PVDD</sub> = 12V
- Extensive Click-and-Pop Suppression
- Space Saving, 30-Bump WLP Package (2.1mm x 2.6mm x 0.6mm, 0.4mm Pitch)

### Simplified Block Diagram



**Ordering Information** appears at end of data sheet.

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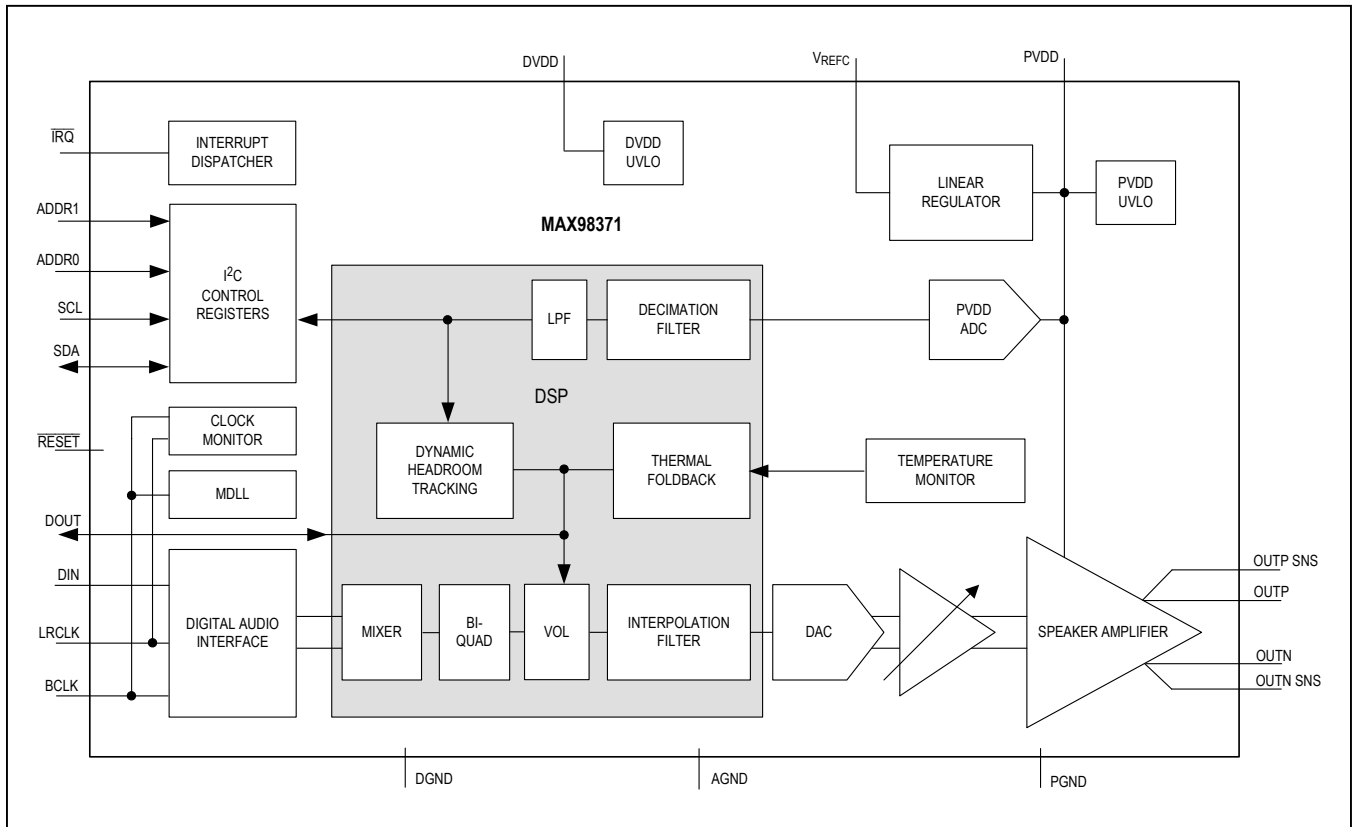

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Detailed Functional Diagram



**Absolute Maximum Ratings**

PVDD to PGND .....-0.3V to 20V  
 OUT\_ to PGND .....-0.3V to (V<sub>PVDD</sub> + 0.3V)  
 V<sub>REFC</sub> to AGND .....-0.3V to 2.2V  
 DVDD to DGND.....-0.3V to 2.2V  
 SDA, SCL, ADDR\_, IRQ to DGND.....-0.3V to 2.2V  
 BCLK, LRCLK, DIN,  
 RESET to DGND .....-0.3V to (V<sub>DVDD</sub> + 0.3V)  
 AGND, DGND to PGND .....-0.1V to 0.1V

Short-Circuit Duration  
 Between OUTP, OUTN and PGND or PVDD ..... Continuous  
 Between OUTP and OUTN ..... Continuous  
 Continuous Power Dissipation (T<sub>A</sub> = +70°C) for Multilayer Board  
 (derate 27mW/°C above +70°C) ..... 1.9W  
 Junction Temperature ..... 150°C  
 Operating Temperature Range .....-40°C to 85°C  
 Storage Temperature Range .....-65°C to 150°C  
 Soldering Temperature (reflow) ..... 260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**Package Thermal Characteristics (Note 1)**

Junction-to-Ambient Thermal Resistance (θ<sub>JA</sub>) ..... 37°C/W  
 Junction-to-Board Thermal Resistance (θ<sub>JB</sub>).....33.4°C/W

**Note 1:** Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to [www.maximintegrated.com/thermal-tutorial](http://www.maximintegrated.com/thermal-tutorial).

**Electrical Characteristics**

(V<sub>PVDD</sub> = 12V, V<sub>DVDD</sub> = RESET = 1.8V, V<sub>GND</sub> = 0V, C<sub>PVDD</sub> = 1x 220µF, 2x 10µF, 2x 0.1µF, C<sub>REFC</sub> = 1µF, C<sub>DVDD</sub> = 1µF, Z<sub>SPK</sub> = open, AC measurement bandwidth 20Hz to 22kHz, f<sub>S</sub> = 48kHz, 24-bit data, T<sub>A</sub> = T<sub>MIN</sub> to T<sub>MAX</sub>, unless, otherwise noted. Typical values are at T<sub>A</sub> = +25°C.) (Note 2)

PARAMETER	SYMBOL	CONDITION		MIN	TYP	MAX	UNITS
Power Supply Voltage Range	V <sub>PVDD</sub>			5.5		18	V
				1.14		1.98	
VREFC Regulator Output	V <sub>REFC</sub>				2.0		V
PVDD Under Voltage Lockout	PVDD UVLO			3.65	4.3	4.75	V
DVDD Under Voltage Lockout	DVDD UVLO				0.75		V
Quiescent Current	I <sub>Q_PVDD</sub>	SPK_SWCLK = 0	472kHz		8.4	12	mA
		SPK_SWCLK = 1	330kHz		7		
Quiescent Current	I <sub>Q_DVDD</sub>				1.5	2.5	mA
Software Shutdown Supply Current	I <sub>SHDN_SW</sub>	All DAI pins pulled low, T <sub>A</sub> = +25°C	I <sub>PVDD</sub>			10	µA
			I <sub>DVDD</sub>			10	
Hardware Shutdown Supply Current	I <sub>SHDN_HW</sub>	RESET = 0V, T <sub>A</sub> = +25°C	I <sub>PVDD</sub>			5	µA
			I <sub>DVDD</sub>			1	
Turn-On Time	t <sub>ON</sub>	From SW_EN bit set to full operation	Volume ramping disabled		10		ms
			Volume ramping enabled		30		



**Electrical Characteristics (continued)**

( $V_{PVDD} = 12V$ ,  $V_{DVDD} = V_{RESET} = 1.8V$ ,  $V_{GND} = 0V$ ,  $C_{PVDD} = 1 \times 220\mu F$ ,  $2 \times 10\mu F$ ,  $2 \times 0.1\mu F$ ,  $C_{REFC} = 1\mu F$ ,  $C_{DVDD} = 1\mu F$ ,  $Z_{SPK} = \text{open}$ , AC measurement bandwidth 20Hz to 22kHz,  $f_S = 48\text{kHz}$ , 24-bit data,  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless, otherwise noted. Typical values are at  $T_A = +25^\circ\text{C}$ .) (Note 2)

PARAMETER	SYMBOL	CONDITION		MIN	TYP	MAX	UNITS
Turn-Off Time	$t_{OFF}$	From SW_EN bit cleared to shutdown	Volume ramping disabled		10		ms
			Volume ramping enabled		30		
<b>DIGITAL FILTER CHARACTERISTICS (LRCLK &lt; 50kHz) (Note 5)</b>							
Passband Cutoff	$f_{PLP}$	Ripple limit cutoff		0.43 x $f_S$		Hz	
		-3dB cutoff		0.47 x $f_S$			
		-6.02dB cutoff		0.5 x $f_S$			
Passband Ripple		$f < f_{PLP}$		-0.1	+0.1	dB	
Stopband Cutoff	$f_{SLP}$				0.58 x $f_S$	Hz	
Stopband Attenuation		$f > f_{SLP}$		60		dB	
<b>DIGITAL FILTER CHARACTERISTICS (LRCLK &gt; 50kHz) (Note 5)</b>							
Passband Cutoff	$f_{PLP}$	Ripple limit cutoff		0.24 x $f_S$		Hz	
		-3dB cutoff		0.31 x $f_S$			
Passband Ripple		$f < f_{PLP}$		-0.1	+0.1	dB	
Stopband Cutoff	$f_{SLP}$				0.417 x $f_S$	Hz	
Stopband Attenuation		$f > f_{SLP}$		60		dB	
<b>DIGITAL HIGHPASS FILTER CHARACTERISTICS</b>							
DC Attenuation (Note 5)				80		dB	
DC Blocking Cutoff Frequency (Note 5)		Across all sample rates	DACHPF = 0x1		2	Hz	
Highpass Cutoff Frequency		Across all sample rates	DACHPF = 0x2	50	Hz		
			DACHPF = 0x3	100			
			DACHPF = 0x4	200			
			DACHPF = 0x5	400			
			DACHPF = 0x6	800			
<b>SPEAKER AMPLIFIER ELECTRICAL CHARACTERISTICS</b>							
<b>DIGITAL VOLUME CONTROL</b>							
Digital Volume (max)		DVOL[6:0] = 0x00		0		dB	
Digital Volume (min)		DVOL[6:0] = 0x7E		-63		dB	
Volume Control Step Size				0.5		dB	
Output Offset Voltage	VOS	$T_A = +25^\circ\text{C}$		$\pm 1$	$\pm 5$	mV	
Click-and-Pop Level	$K_{CP}$	Peak voltage, $T_A = +25^\circ\text{C}$ , A-weighted, 32 samples per second, digital audio inputs have zero-code input	Into shutdown	-66	dBV		
			Out of shutdown	-60			

**Electrical Characteristics (continued)**

(V<sub>PVDD</sub> = 12V, V<sub>DVDD</sub> = V<sub>RESET</sub> = 1.8V, V<sub>GND</sub> = 0V, C<sub>PVDD</sub> = 1x 220µF, 2x 10µF, 2x 0.1µF, C<sub>REFC</sub> = 1µF, C<sub>DVDD</sub> = 1µF, Z<sub>SPK</sub> = open, AC measurement bandwidth 20Hz to 22kHz, f<sub>S</sub> = 48kHz, 24-bit data, T<sub>A</sub> = T<sub>MIN</sub> to T<sub>MAX</sub>, unless, otherwise noted. Typical values are at T<sub>A</sub> = +25°C.) (Note 2)

PARAMETER	SYMBOL	CONDITION		MIN	TYP	MAX	UNITS
Dynamic Range	DR	V <sub>PVDD</sub> = 17V, Z <sub>L</sub> = 8Ω + 33µH, measured using the EIAJ method, -60dBFS 1kHz output signal, referenced to 1% output power	A-weighted		110		dB
Integrated Output Noise	e <sub>N</sub>	Z <sub>L</sub> = 8Ω + 33µH	A-weighted		35		µV <sub>RMS</sub>
			Unweighted		72		
Output Power	P <sub>OUT</sub>	THD+N ≤ 1%, f = 1kHz	Z <sub>L</sub> = 8Ω + 33µH		8.2		W
			Z <sub>L</sub> = 8Ω + 33µH, V <sub>PVDD</sub> = 17V		15.7		
			Z <sub>L</sub> = 4Ω + 33µH		13.2		
		THD+N ≤ 10%, f = 1kHz	Z <sub>L</sub> = 8Ω + 33µH		10.2		
			Z <sub>L</sub> = 8Ω + 33µH, V <sub>PVDD</sub> = 17V		19		
			Z <sub>L</sub> = 4Ω + 33µH		15.8		
Efficiency	η <sub>SPK</sub>	f = 1kHz	P <sub>OUT</sub> = 10W, Z <sub>L</sub> = 8Ω + 33µH		91		%
			P <sub>OUT</sub> = 15W, Z <sub>L</sub> = 4Ω + 33µH		81		
Total Harmonic Distortion + Noise	THD+N	f = 1kHz	P <sub>OUT</sub> = 4W, Z <sub>L</sub> = 8Ω + 33µH		0.02		%
			P <sub>OUT</sub> = 8W, Z <sub>L</sub> = 4Ω + 33µH		0.03		
		f = Up to 6kHz	P <sub>OUT</sub> = 4W, Z <sub>L</sub> = 8Ω + 33µH		0.1		
			P <sub>OUT</sub> = 8W, Z <sub>L</sub> = 4Ω + 33µH		0.2		
Maximum Frequency Response Deviation		Maximum deviation above and below 1kHz reference			0.2		dB
Gain Error	A <sub>VE</sub>	f=1kHz, V <sub>O</sub> = 2.828V <sub>RMS</sub>		-0.5		+0.5	dB
Maximum Channel-to-Channel Phase Error (Note 3)		Output phase shift between multiple devices from 20Hz to 20kHz, across all sample rates and DAI operating modes			1		deg

## Electrical Characteristics (continued)

( $V_{PVDD} = 12V$ ,  $V_{DVDD} = V_{RESET} = 1.8V$ ,  $V_{GND} = 0V$ ,  $C_{PVDD} = 1 \times 220\mu F$ ,  $2 \times 10\mu F$ ,  $2 \times 0.1\mu F$ ,  $C_{REFC} = 1\mu F$ ,  $C_{DVDD} = 1\mu F$ ,  $Z_{SPK} = \text{open}$ , AC measurement bandwidth 20Hz to 22kHz,  $f_S = 48\text{kHz}$ , 24-bit data,  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless, otherwise noted. Typical values are at  $T_A = +25^\circ\text{C}$ .) (Note 2)

PARAMETER	SYMBOL	CONDITION	MIN	TYP	MAX	UNITS
PVDD Power Supply Rejection Ratio	PSRR	$V_{PVDD} = 5.5V$ to $18V$		85		dB
		$f = 20\text{Hz}$ to $10\text{kHz}$ , $V_{RIPPLE} = 100\text{mV}_{P-P}$		75		
		$f = 10\text{kHz}$ to $20\text{kHz}$ , $V_{RIPPLE} = 100\text{mV}_{P-P}$		60		
DVDD Power Supply Rejection Ratio	PSRR	$f = 1\text{kHz}$ , $V_{RIPPLE} = 50\text{mV}_{P-P}$		100		
Output Switching Frequency	$f_S$	Constant across all sample rates	SPK_SWCLK = 0	472		kHz
			SPK_SWCLK = 1	330		kHz
Output Stage On-Resistance	$R_{ON}$	PMOS + NMOS		0.425		$\Omega$
Current Limit	$I_{LIM}$	$Z_L = 8\Omega + 33\mu H$ or $Z_L = 4\Omega + 33\mu H$	4.5	6.0		A
<b>THERMAL FOLDBACK</b>						
Attack Time				10		$\mu\text{s}$
Attenuation Slope		THRM_SLOPE[1:0] = 0x0		0.5		dB/ $^\circ\text{C}$
		THRM_SLOPE[1:0] = 0x1		1		
		THRM_SLOPE[1:0] = 0x2		2		
Maximum Attenuation				12		dB
Release Time		THRM_REL[1:0] = 0x0		3		ms/dB
		THRM_REL[1:0] = 0x3		300		
<b>THERMAL SHUTDOWN</b>						
Trigger Point		(Note 3)	140	150	160	$^\circ\text{C}$
Hysteresis				20		$^\circ\text{C}$
<b>PVDD ADC ELECTRICAL CHARACTERISTICS</b>						
Resolution				8		Bits
Absolute Error				1.2		LSB
ADC Voltage Range			5.35		18.15	V
ADC Lowpass Filter Cutoff Frequency		-3dB limit		$0.0875 \times f_S$		Hz

**Electrical Characteristics (continued)**

( $V_{PVDD} = 12V$ ,  $V_{DVDD} = V_{RESET} = 1.8V$ ,  $V_{GND} = 0V$ ,  $C_{PVDD} = 1 \times 220\mu F$ ,  $2 \times 10\mu F$ ,  $2 \times 0.1\mu F$ ,  $C_{REFC} = 1\mu F$ ,  $C_{DVDD} = 1\mu F$ ,  $Z_{SPK} = \text{open}$ , AC measurement bandwidth 20Hz to 22kHz,  $f_S = 48\text{kHz}$ , 24-bit data,  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless, otherwise noted. Typical values are at  $T_A = +25^\circ\text{C}$ .) (Note 2)

PARAMETER	SYMBOL	CONDITION	MIN	TYP	MAX	UNITS
ADC Lowpass Filter Stopband Frequency		-40dB limit		0.167 $\times f_S$		Hz
ADC Programmable Lowpass Filter		PVDD_ADC_BW[1:0] = 0x1		2		Hz
		PVDD_ADC_BW[1:0] = 0x2		20		
		PVDD_ADC_BW[1:0] = 0x3		200		
<b>DIGITAL I/O CHARACTERISTICS</b>						
<b>DIN, BCLK, LRCLK, ADDR_, RESET</b>						
Input Voltage High	$V_{IH}$		0.7 x $V_{DVDD}$			V
Input Voltage Low	$V_{IL}$			0.3 x $V_{DVDD}$		V
Input Leakage Current	$I_{IH}, I_{IL}$		-1		+1	$\mu\text{A}$
Input Capacitance	$C_{IN}$			3		pF
<b>INPUT (SDA, SCL)</b>						
Input Voltage High	$V_{IH}$		0.7 x $V_{DVDD}$			V
Input Voltage Low	$V_{IL}$			0.3 x $V_{DVDD}$		V
Input Hysteresis	$V_{HYS}$			200		mV
Input Capacitance	$C_{IN}$			3		pF
Input Leakage Current	$I_{IH}, I_{IL}$	$T_A = +25^\circ\text{C}$ , input high	-1		+1	$\mu\text{A}$
<b>OUTPUT (SDA, IRQ)</b>						
Output Low Voltage	$V_{OL}$	$I_{SINK} = 3\text{mA}$			0.4	V
Output Current	$I_{OL}$			13		mA
<b>DIGITAL AUDIO INTERFACE TIMING CHARACTERISTICS</b>						
<b>GLOBAL</b>						
LRCLK Frequency Range	$f_{LRCLK}$	All DAI operating modes	32		96	kHz
Word Length		All DAI operating modes		16		bits
				24		
				32		
BCLK Duty Cycle			45		55	%
Maximum BCLK/LRCLK Input Jitter		Maximum jitter with minimal performance degradation	RMS jitter below 40kHz	0.5		ns
			RMS jitter above 40kHz	0.9		

**Electrical Characteristics (continued)**

(V<sub>PVDD</sub> = 12V, V<sub>DVDD</sub> = V<sub>RESET</sub> = 1.8V, V<sub>GND</sub> = 0V, C<sub>PVDD</sub> = 1x 220µF, 2x 10µF, 2x 0.1µF, C<sub>REFC</sub> = 1µF, C<sub>DVDD</sub> = 1µF, Z<sub>SPK</sub> = open, AC measurement bandwidth 20Hz to 22kHz, f<sub>S</sub> = 48kHz, 24-bit data, T<sub>A</sub> = T<sub>MIN</sub> to T<sub>MAX</sub>, unless, otherwise noted. Typical values are at T<sub>A</sub> = +25°C.) (Note 2)

PARAMETER	SYMBOL	CONDITION	MIN	TYP	MAX	UNITS
<b>PCM MODE (I<sup>2</sup>S, LEFT-JUSTIFIED)</b>						
LRCLK Duty Cycle			45		55	%
LRCLK to BCLK Active Edge Setup Time	t <sub>SYNCSET</sub>		10			ns
LRCLK to BCLK Active Edge Hold Time	t <sub>SYNHOLD</sub>		10			ns
DIN to BCLK Active Edge Setup Time	t <sub>SETUP</sub>		10			ns
DIN to BCLK Active Edge Hold Time	t <sub>HOLD</sub>		10			ns
BCLK Period (Note 3)	t <sub>BCLK</sub>		160			ns
BCLK Frequency (Note 3)	f <sub>BCLK</sub>				6.25	MHz
					f <sub>S</sub> x 32	
					f <sub>S</sub> x 48	
					f <sub>S</sub> x 64	
<b>TDM MODE</b>						
LRCLK Pulse Width	PW <sub>LRCLK</sub>	Measured in number of BCLK cycles			511	cycles
DIN Frame Delay after LRCLK Edge		Measured in number of BCLK cycles	0		2	cycles
BCLK Period (Note 3)	t <sub>BCLK</sub>		20			ns
BCLK Frequency (Note 3)	f <sub>BCLK</sub>	All TDM operating modes			50	MHz

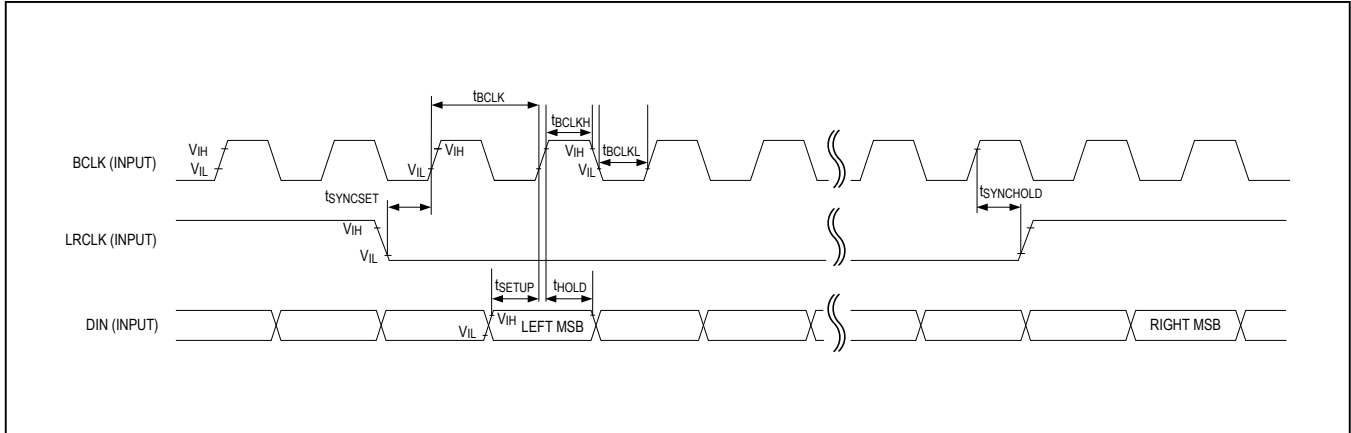


Figure 1. I<sup>2</sup>S Audio Interface Timing Diagram

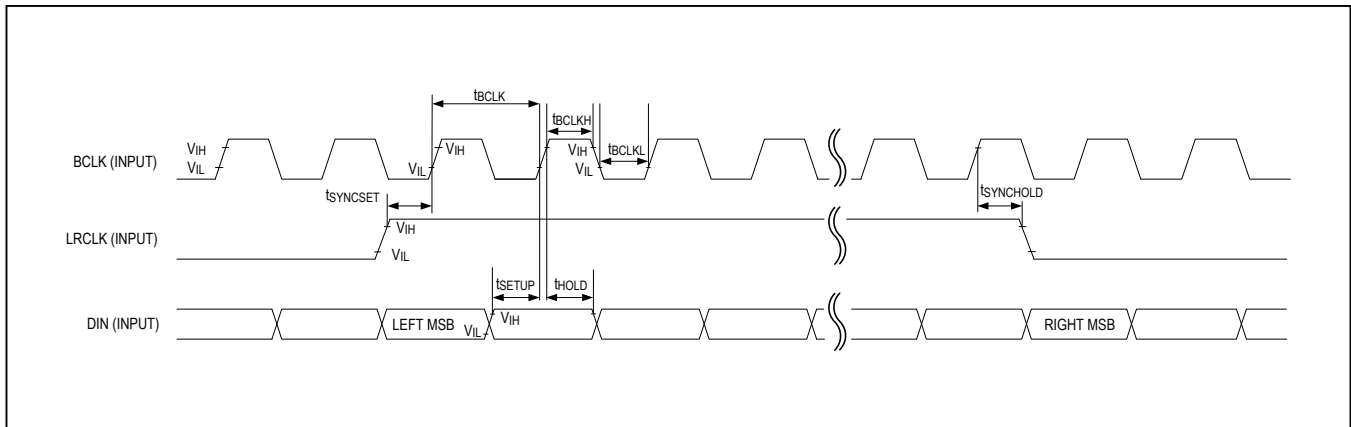


Figure 2. Left-Justified Audio Interface Timing Diagram

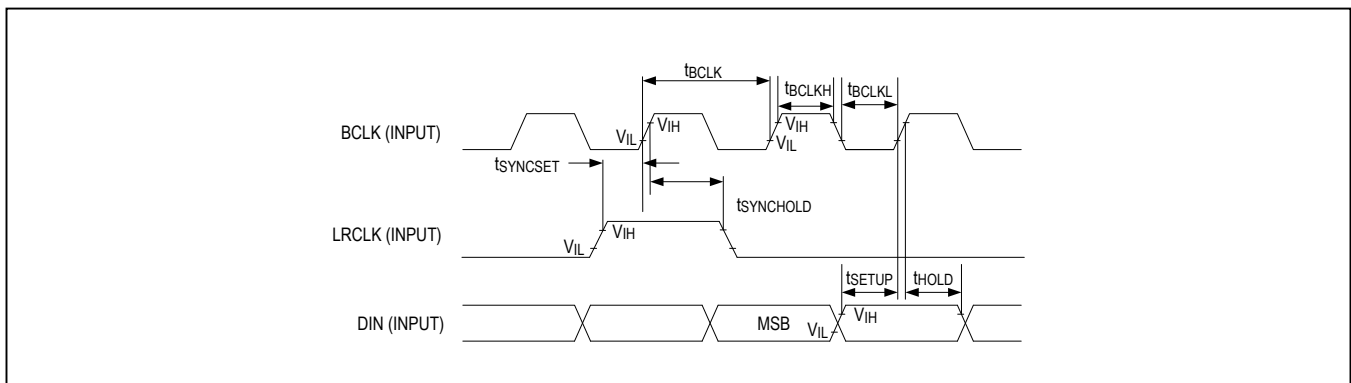


Figure 3. TDM Audio Interface Timing Diagrams

**I<sup>2</sup>C Timing Characteristics**

(V<sub>PVDD</sub> = 12V, V<sub>DVDD</sub> = V<sub>RESET</sub> = 1.8V, V<sub>GND</sub> = 0V, C<sub>PVDD</sub> = 1x 220µF, 2x 10µF, 2x 0.1µF, C<sub>VREFC</sub> = 1µF, C<sub>DVDD</sub> = 1µF, Z<sub>SPK</sub> = open, AC measurement bandwidth 20Hz to 22kHz, f<sub>S</sub> = 48kHz, 24-bit data, T<sub>A</sub> = T<sub>MIN</sub> to T<sub>MAX</sub>, unless, otherwise noted. Typical values are at T<sub>A</sub> = +25°C.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
<b>I<sup>2</sup>C TIMING CHARACTERISTICS</b>						
Serial Clock Frequency	f <sub>SCL</sub>		0		400	kHz
Bus Free Time Between STOP and START Conditions	t <sub>BUF</sub>		1.3			µs
Hold Time (Repeated) START Condition	t <sub>HD,STA</sub>		0.6			µs
SCL Pulse-Width Low	t <sub>LOW</sub>		1.3			µs
SCL Pulse-Width High	t <sub>HIGH</sub>		0.6			µs
Setup Time for a Repeated START Condition	t <sub>SU,STA</sub>		0.6			µs
Data Hold Time	t <sub>HD,DAT</sub>		0		900	ns
Data Setup Time	t <sub>SU,DAT</sub>		100			ns
SDA and SCL Receiving Rise Time (Note 4)	t <sub>R</sub>		20 + 0.1C <sub>B</sub>		300	ns
SDA and SCL Receiving Fall Time (Note 4)	t <sub>F</sub>		20 + 0.1C <sub>B</sub>		300	ns
SDA Transmitting Fall Time	t <sub>F</sub>		20		250	ns
Setup Time for STOP Condition	t <sub>SU,STO</sub>		0.6			µs
Bus Capacitance	C <sub>B</sub>				400	pF
Pulse Width of Suppressed Spike	t <sub>SP</sub>		0		50	ns

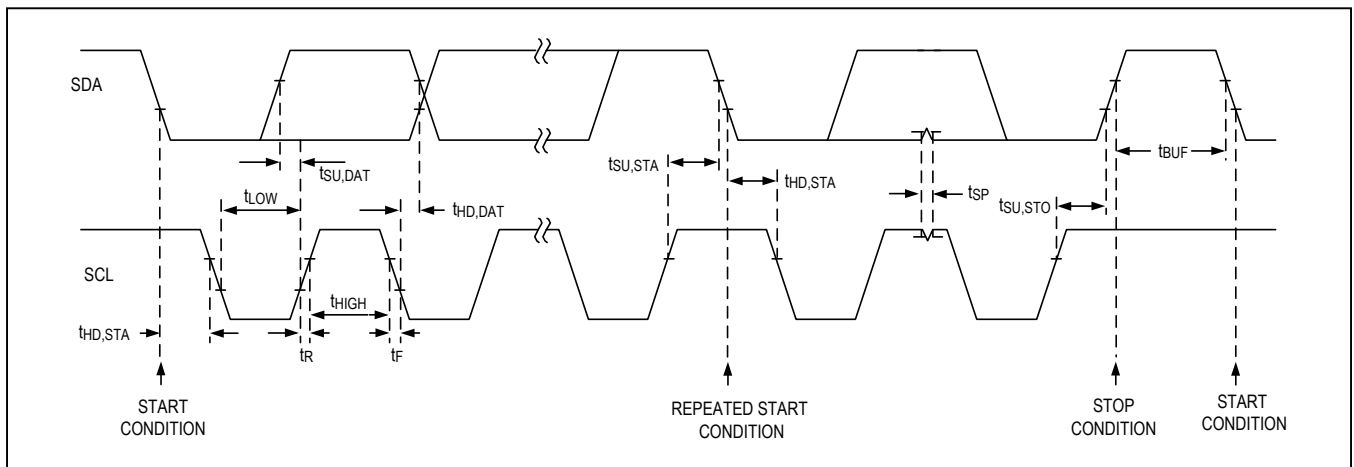


Figure 4. I<sup>2</sup>C Interface Timing Diagram

## Power Consumption

( $V_{PVDD} = 12V$ ,  $V_{DVDD} = V_{\overline{RESET}} = 1.8V$ ,  $V_{GND} = 0V$ ,  $C_{PVDD} = 1 \times 220\mu F, 2 \times 10\mu F, 2 \times 0.1\mu F$ ,  $C_{VREFC} = 1\mu F$ ,  $C_{DVDD} = 1\mu F$ ,  $Z_{SPK} = \text{open}$ , AC measurement bandwidth 20Hz to 22kHz,  $f_S = 48kHz$ , 24-bit data,  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless, otherwise noted. Typical values are at  $T_A = +25^\circ C$ .) (Note 2)

CONDITION	$I_{PVDD}$ (mA)	$P_{PVDD}$ (mW)	$I_{DVDD}$ (mA)	$P_{DVDD}$ (mW)	$P_{TOTAL}$ (mW)
<b><math>f_{SPK} = 330kHz</math></b>					
PCM to SPK	7.0	84.0	1.3	2.3	86.3
PCM to SPK, DHT	7.3	88.0	1.8	3.3	91.3
PCM to SPK, LMTR	7.0	84.0	1.8	3.2	87.2
<b><math>f_{SPK} = 472kHz</math></b>					
PCM to SPK,	8.4	100.8	1.3	2.3	103.1
PCM to SPK, DHT	8.8	105.6	1.8	3.3	108.9
PCM to SPK, LMTR	8.5	101.5	1.8	3.2	104.7
<b><math>f_{SPK} = 472kHz</math> AND <math>PVDD = 17V</math></b>					
PCM to SPK	9.3	157.7	1.3	2.3	160.0
PCM to SPK, DHT	6.6	163.0	1.8	3.3	166.6
PCM to SPK, LMTR	6.0	157.1	1.8	3.2	160.3

**Note 2:** 100% production tested at  $T_A = +25^\circ C$ . Specifications over temperature limits are guaranteed by design. Typical values are based on 1 sigma characterization data, unless otherwise noted.

**Note 3:** Minimums and/or maximum limits shown are design targets and not 100% production tested. Characterization data is provided to validate device performance.

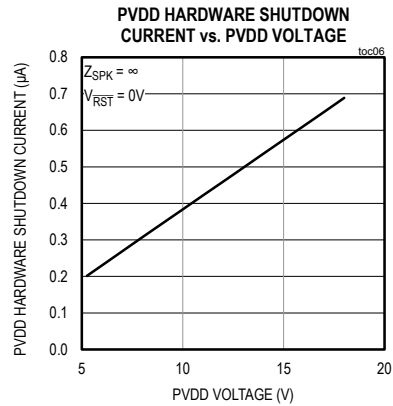
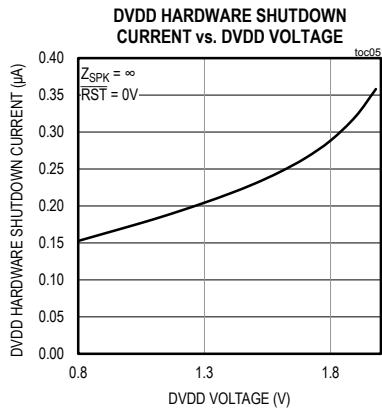
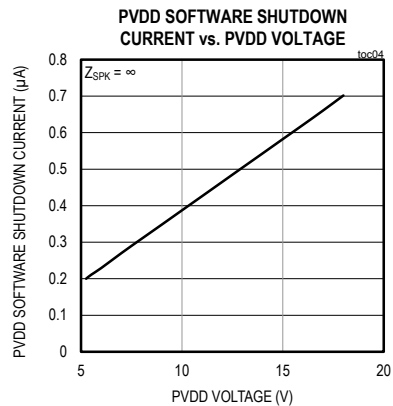
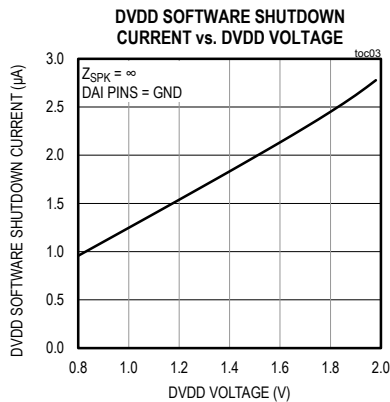
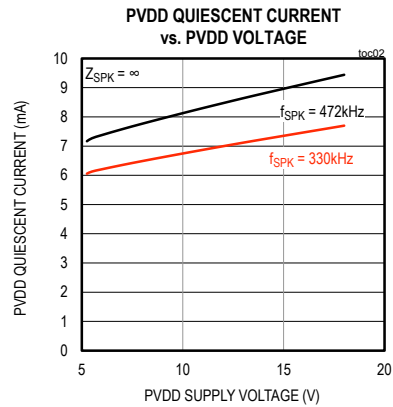
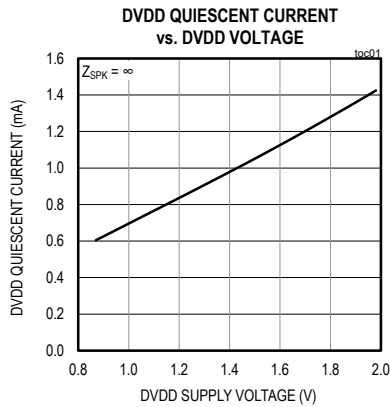
**Note 4:**  $C_B$  in pF.

**Note 5:** Digital filter performance is invariant over temperature and production tested at  $T_A = +25^\circ C$ .



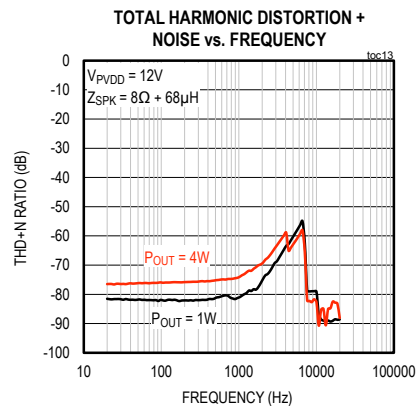
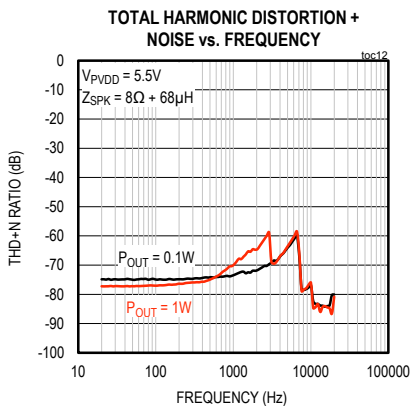
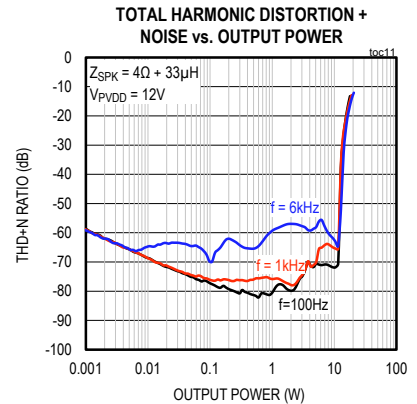
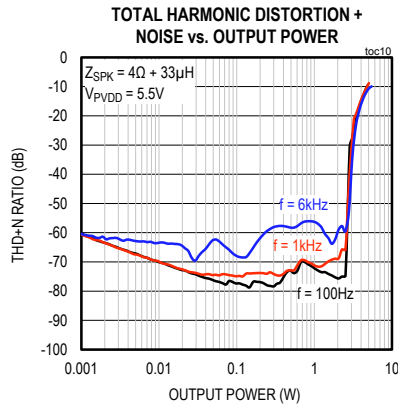
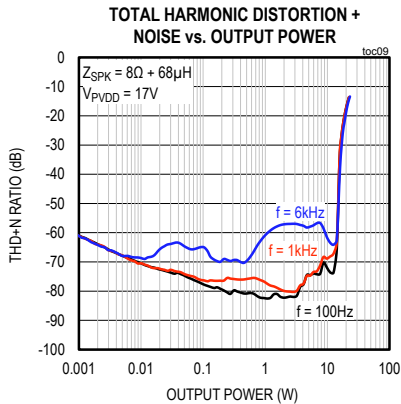
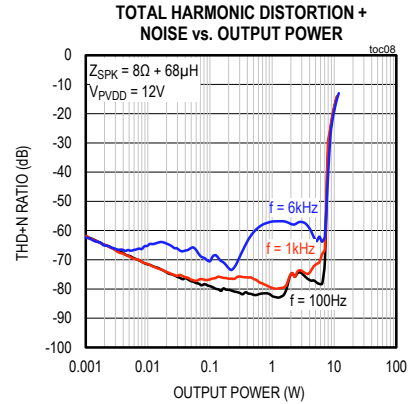
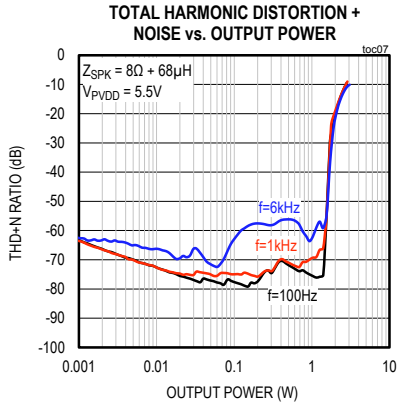
Typical Operating Characteristics

( $V_{PVDD} = 12V$ ,  $V_{DVDD} = 1.8V$ ,  $V_{GND} = 0V$ ,  $SPK\_GAIN\_MAX = 0x0B$  (20.5dB),  $f_{BCLK} = 3.072MHz$ ,  $f_{LRCLK} = 48kHz$ , speaker loads ( $Z_{SPK}$ ) connected between  $OUTP$  and  $OUTN$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_A = +25^\circ C$ .)



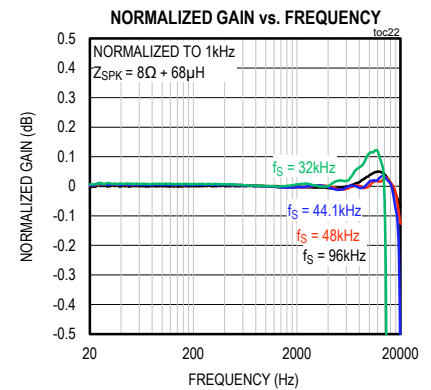
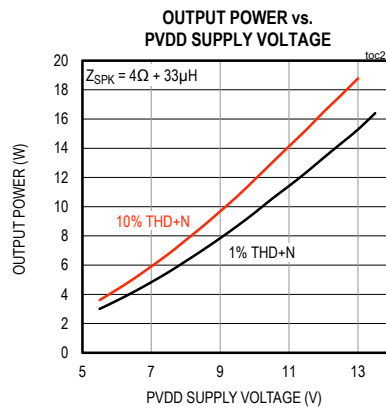
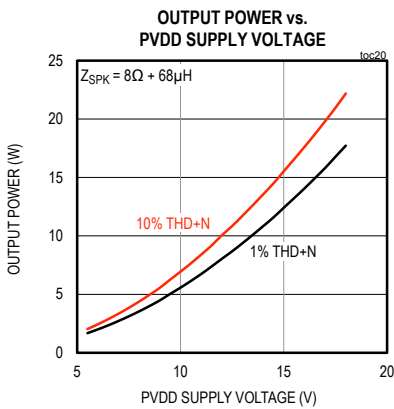
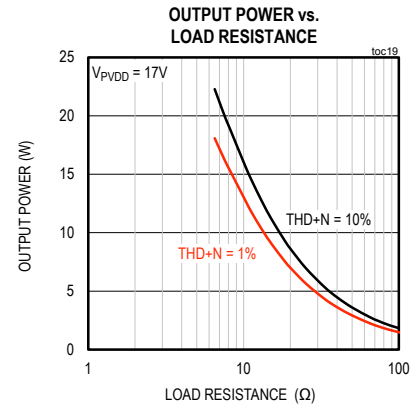
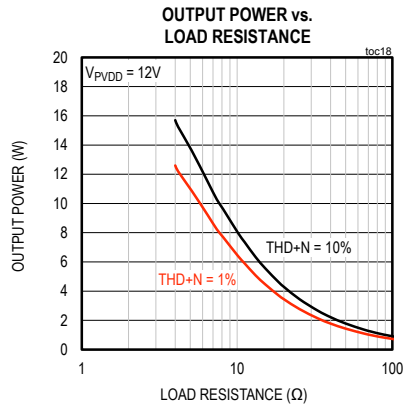
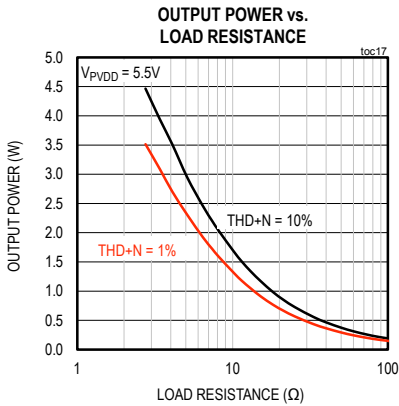
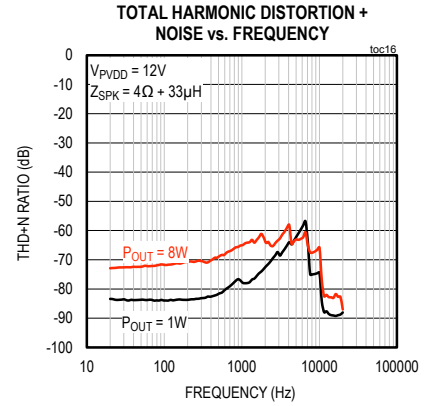
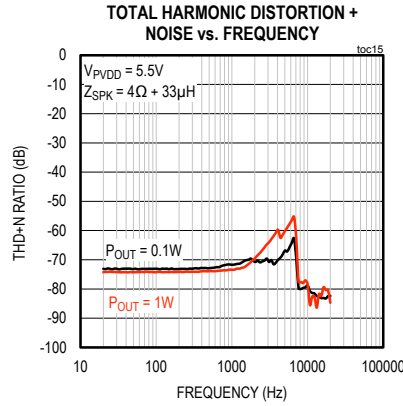
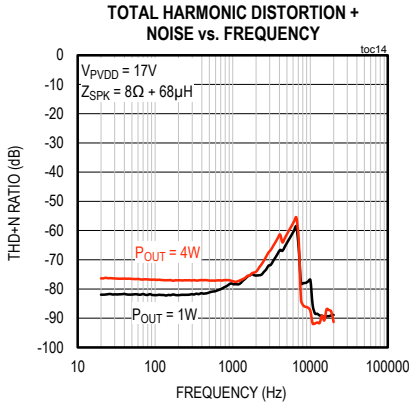
Typical Operating Characteristics (continued)

( $V_{PVDD} = 12V$ ,  $V_{DVDD} = 1.8V$ ,  $V_{GND} = 0V$ ,  $SPK\_GAIN\_MAX = 0x0B$  (20.5dB),  $f_{BCLK} = 3.072MHz$ ,  $f_{LRCLK} = 48kHz$ , speaker loads ( $Z_{SPK}$ ) connected between  $OUTP$  and  $OUTN$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .)



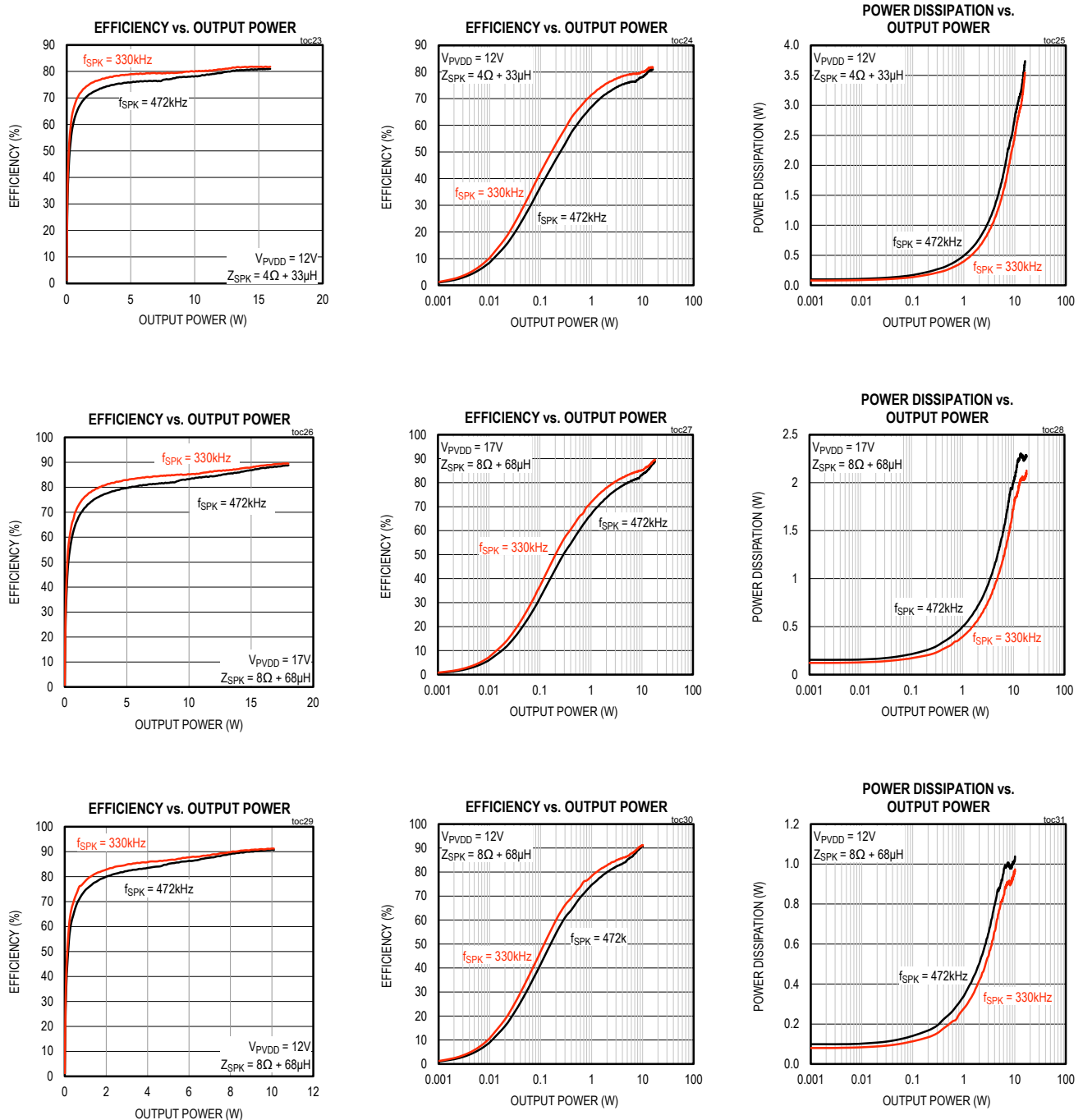
Typical Operating Characteristics (continued)

( $V_{PVDD} = 12V$ ,  $V_{DVDD} = 1.8V$ ,  $V_{GND} = 0V$ ,  $SPK\_GAIN\_MAX = 0x0B$  (20.5dB),  $f_{BCLK} = 3.072MHz$ ,  $f_{LRCLK} = 48kHz$ , speaker loads ( $Z_{SPK}$ ) connected between  $OUTP$  and  $OUTN$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_A = +25^\circ C$ .)



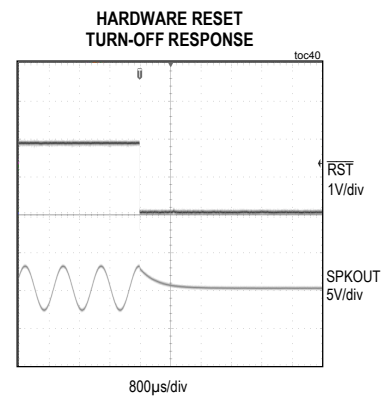
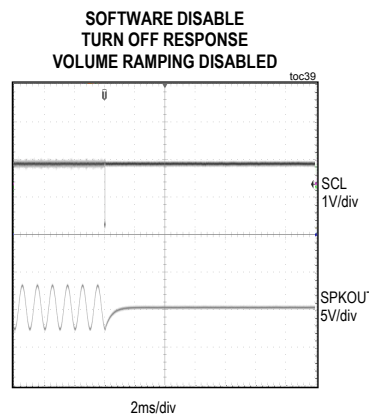
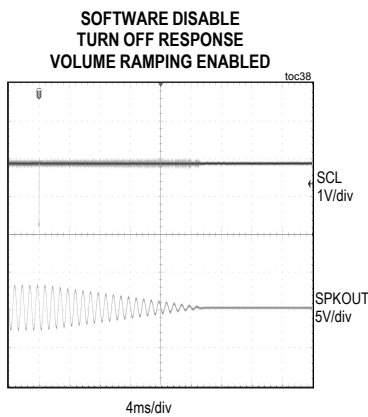
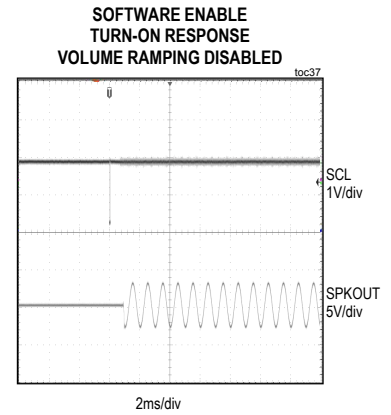
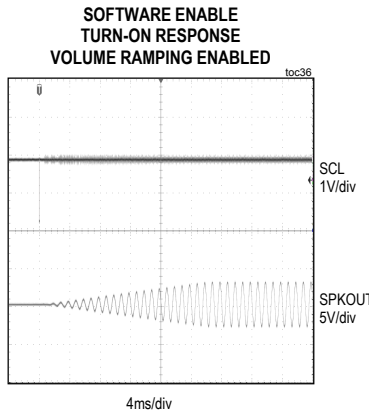
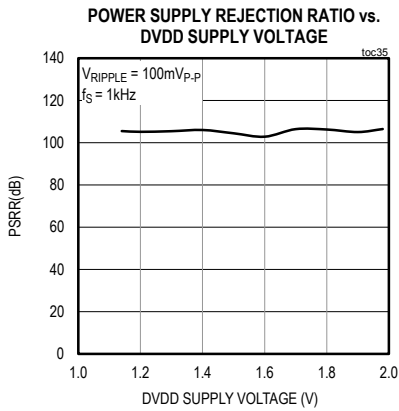
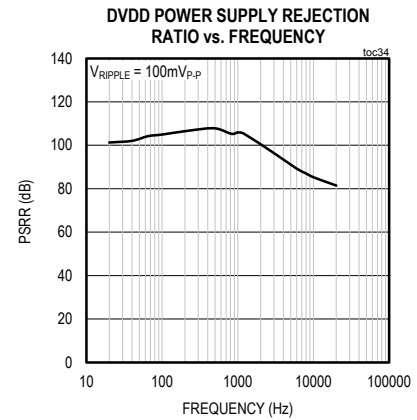
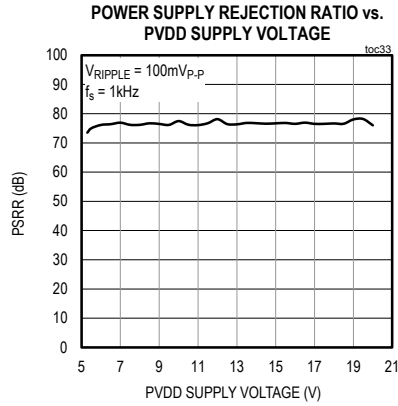
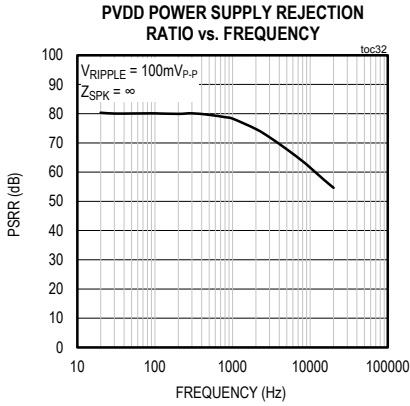
Typical Operating Characteristics (continued)

( $V_{PVDD} = 12V$ ,  $V_{DVDD} = 1.8V$ ,  $V_{GND} = 0V$ ,  $SPK\_GAIN\_MAX = 0x0B$  (20.5dB),  $f_{BCLK} = 3.072MHz$ ,  $f_{LRCLK} = 48kHz$ , speaker loads ( $Z_{SPK}$ ) connected between OUTP and OUTN,  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_A = +25^\circ C$ .)



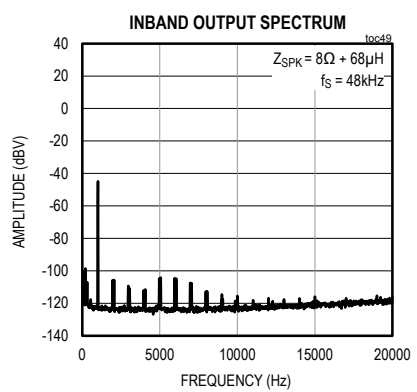
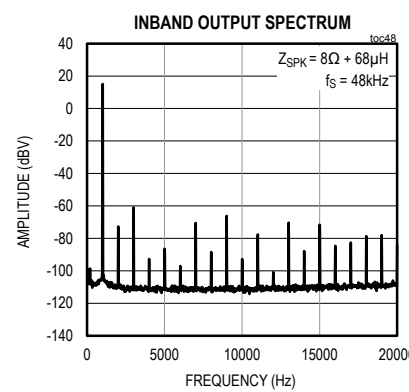
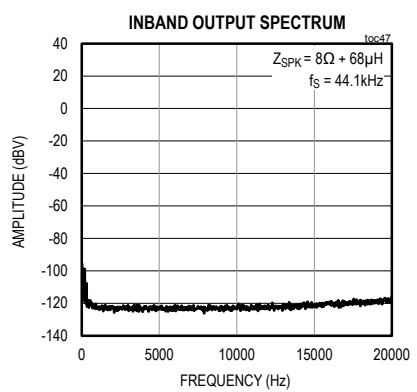
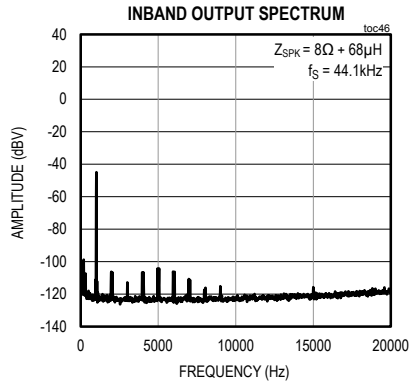
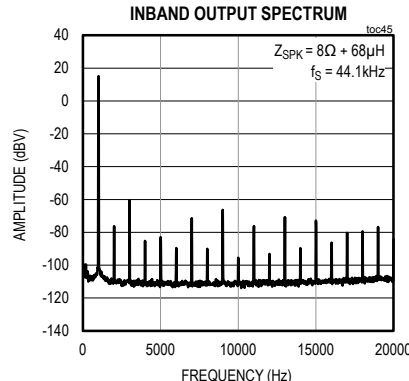
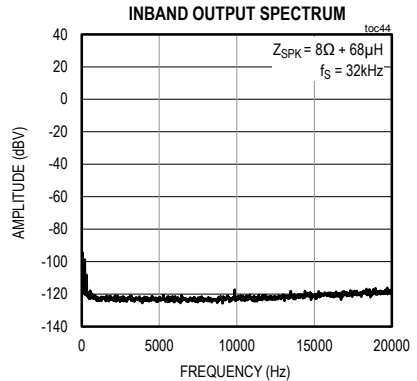
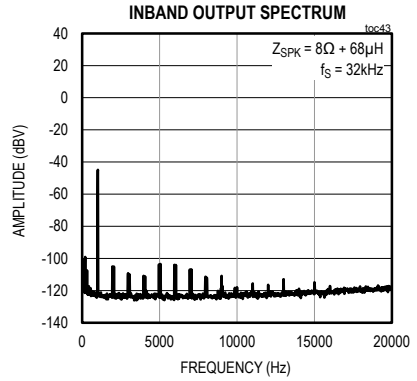
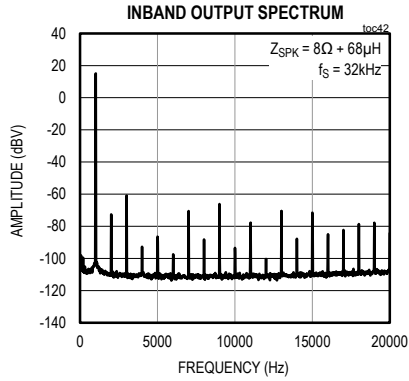
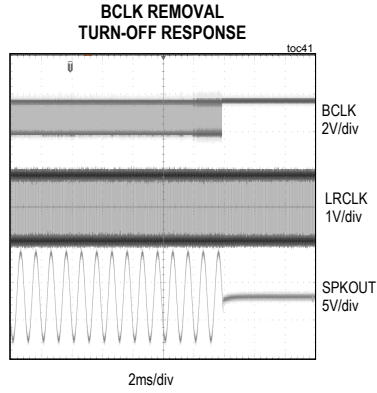
Typical Operating Characteristics (continued)

( $V_{PVDD} = 12V$ ,  $V_{DVDD} = 1.8V$ ,  $V_{GND} = 0V$ ,  $SPK\_GAIN\_MAX = 0x0B$  (20.5dB),  $f_{BLCK} = 3.072MHz$ ,  $f_{LRCLK} = 48kHz$ , speaker loads ( $Z_{SPK}$ ) connected between  $OUTP$  and  $OUTN$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .)



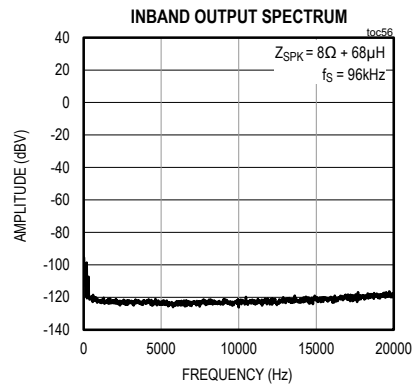
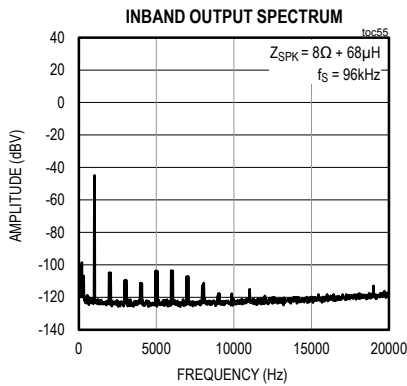
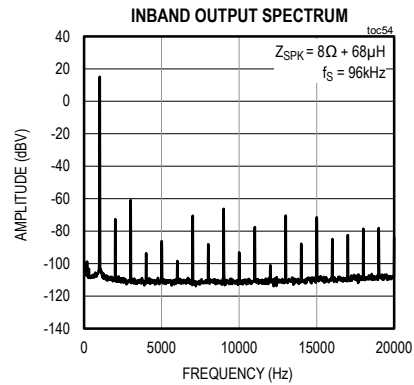
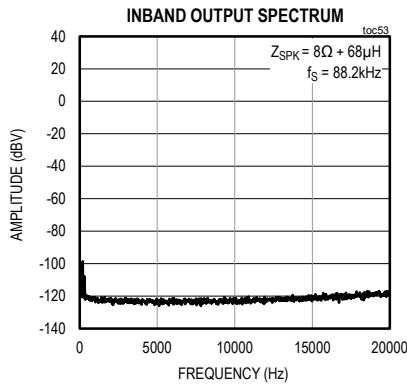
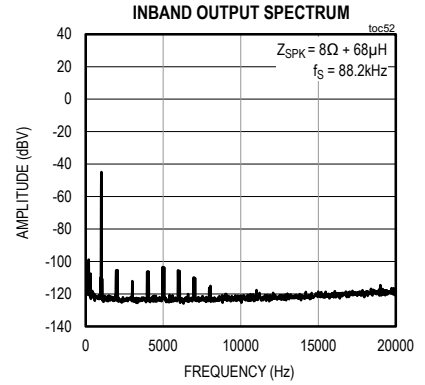
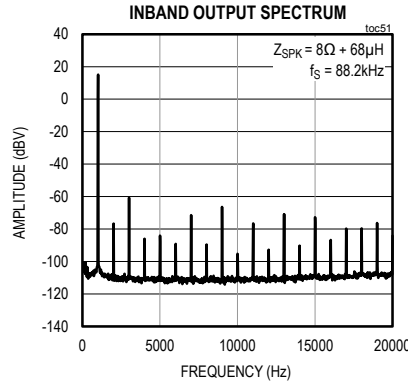
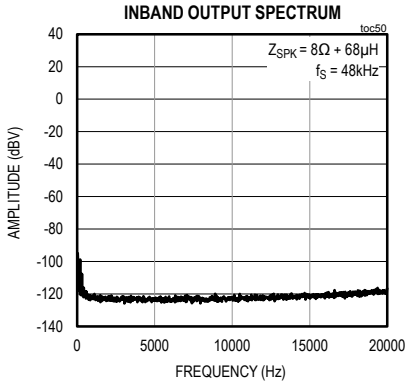
Typical Operating Characteristics (continued)

( $V_{PVDD} = 12V$ ,  $V_{DVDD} = 1.8V$ ,  $V_{GND} = 0V$ ,  $SPK\_GAIN\_MAX = 0x0B$  (20.5dB),  $f_{BCLK} = 3.072MHz$ ,  $f_{LRCLK} = 48kHz$ , speaker loads ( $Z_{SPK}$ ) connected between OUTP and OUTN,  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_A = +25^\circ C$ .)

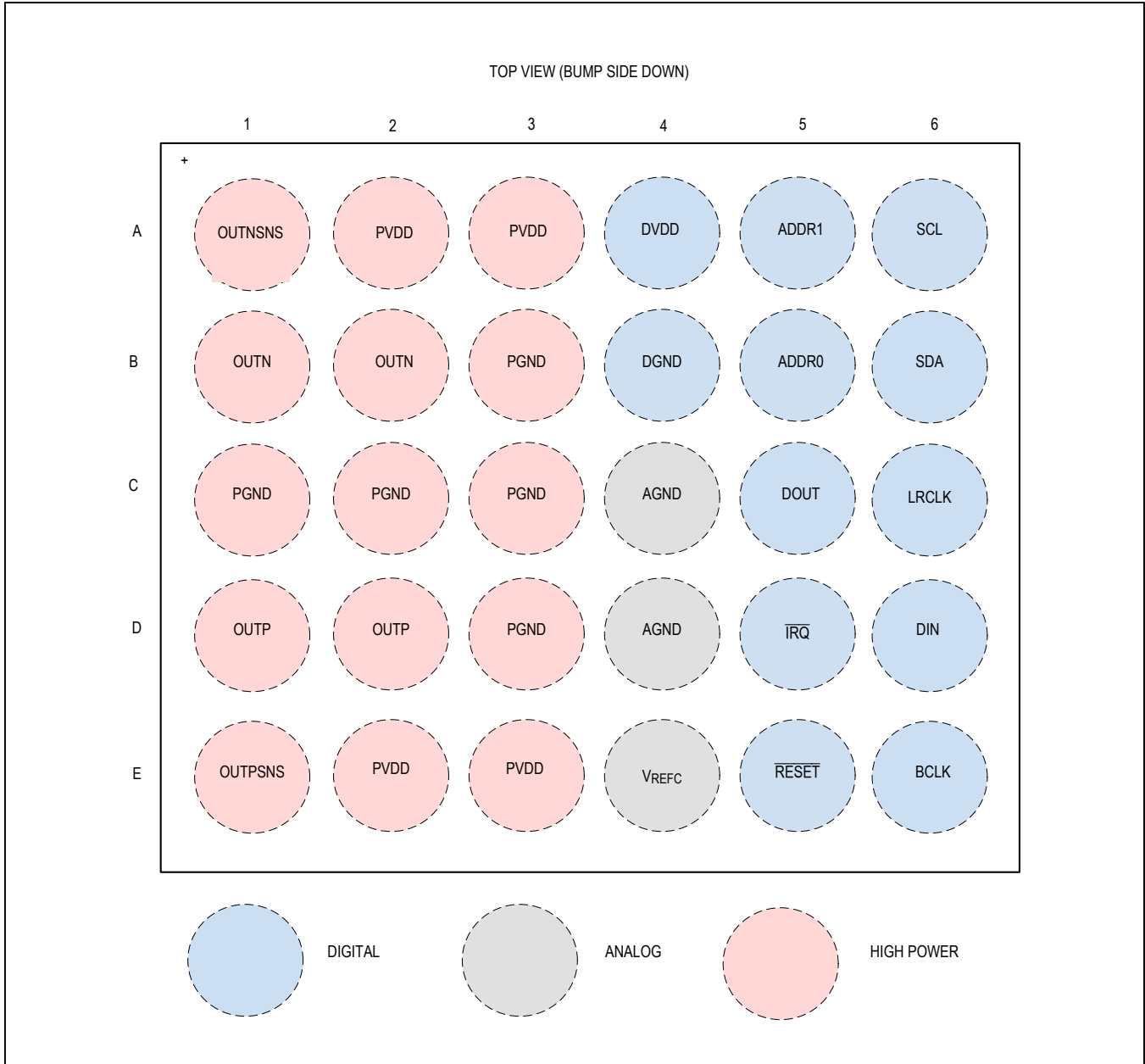


Typical Operating Characteristics (continued)

( $V_{PVDD} = 12V$ ,  $V_{DVDD} = 1.8V$ ,  $V_{GND} = 0V$ ,  $SPK\_GAIN\_MAX = 0x0B$  (20.5dB),  $f_{BCLK} = 3.072MHz$ ,  $f_{LRCLK} = 48kHz$ , speaker loads ( $Z_{SPK}$ ) connected between  $OUTP$  and  $OUTN$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_A = +25^\circ C$ .)



Pin Configuration





## Pin Description

BUMP	NAME	SUPPLY RAIL	FUNCTION
A1	OUTNSNS	PVDD	Negative Speaker Amplifier Output Sense. If not used, connect to OUTN.
A2, A3 E2, E3	PVDD	—	Speaker Amplifier Power Supply. Bypass each bump pair to PGND with a 10 $\mu$ F and a 0.1 $\mu$ F, and a single 220 $\mu$ F per device.
A4	DVDD	—	Digital Core, Digital Audio Interface, and I <sup>2</sup> C Control Power Supply. Bypass to DGND with a 1 $\mu$ F.
A5	ADDR1	DVDD	Four-Level I <sup>2</sup> C Slave Address Select Input. See the <i>Slave Address Selection</i> section for additional information (Table 40).
A6	SCL	DVDD	I <sup>2</sup> C Control Clock Input
B1, B2	OUTN	PVDD	Negative Speaker Amplifier Output
B3, C1–C3, D3	PGND	—	Speaker Amplifier Ground
B4	DGND	—	Digital Ground
B5	ADDR0	DVDD	Four-Level I <sup>2</sup> C Slave Address Select Input. See the <i>Slave Address Selection</i> section for additional information (Table 40).
B6	SDA	DVDD	I <sup>2</sup> C Control Data Input/Output
C4, D4	AGND	—	Analog Ground
C5	DOUT	DVDD	Bidirectional ICC Link Data
C6	LRCLK	DVDD	DAI Left/Right Clock Input. LRCLK is the audio sample rate clock and determines whether audio data is routed to the left or right channel. In TDM mode, LRCLK is a frame sync pulse with programmable width.
D1, D2	OUTP	PVDD	Positive Speaker Amplifier Output
D5	$\overline{\text{IRQ}}$	DVDD	Hardware Interrupt Output. $\overline{\text{IRQ}}$ can be programmed to pull low when individual bits in the flag registers change value. Connect a 10k $\Omega$ pullup resistor for full output swing.
D6	DIN	DVDD	DAI Audio Data Input
E1	OUTPSNS	PVDD	Positive Speaker Amplifier Output Sense. If not used, connect to OUTP.
E4	V <sub>REFC</sub>	PVDD	Internal Regulator Decoupling Point. Bypass to AGND with a 1 $\mu$ F.
E5	$\overline{\text{RESET}}$	DVDD	Active-Low Hardware Reset. Drive low to place the device into low power reset mode and reset the device registers to their power-on-reset (POR) states.
E6	BCLK	DVDD	DAI Bit Clock Input

**Detailed Description**

The MAX98371 is a high-efficiency mono Class D audio amplifier that features thermal foldback protection and ADCs for sensing battery supply voltage and onboard temperature.

The MAX98371 can operate over a wide range of supply voltage (PVDD), and has extensive on-board digital signal processing to enable dynamic headroom tracking (DHT). This feature automatically adjusts the output signal to fit into the available supply voltage range. The DHT can be completely bypassed for operation with fixed, regulated supply voltages.

Active emissions limiting edge rate and overshoot control circuitry, together with Class D modulation minimize the electromagnetic interference (EMI) traditionally associated with Class D amplifiers. In systems that use less than 18 inches of speaker cable, an output filter is unnecessary to meet standard EMI limits.

Two ADCs monitor PVDD supply voltage and die temperature. The PVDD supply voltage value can be read using the I<sup>2</sup>C interface. The temperature ADC can be read back through I<sup>2</sup>C, however, accurate readings only occur after the die temperature exceeds +100°C.

The DAI supports I<sup>2</sup>S, left-justified, and TDM formatted data at the following sample rates: 32kHz, 44.1kHz, 48kHz, 88.2kHz, and 96kHz. Audio bit depths of 16, 24, and 32 bits are supported for input data. The DAI operates from BCLK to allow the device to function without MCLK.

Thermal foldback allows the device to smoothly attenuate the audio output in an effort to prevent destructive thermal behavior. Above a set threshold, the gain of the replay path reduces at a (user programmable) dB/°C rate to a 12dB maximum attenuation. Thermal monitoring capabilities alert the host when die temperature has triggered the thermal foldback circuit, or is approaching the maximum operating temperature. If maximum die temperature is exceeded, the device shuts down to protect itself. Short-circuit protection ensures that accidental shorts or high-current events do not cause damage to the IC.

Device status is communicated to the host through a hardware interrupt (IRQ) and status registers accessible through the I<sup>2</sup>C interface.

The MAX98371 is fully programmable through the I<sup>2</sup>C interface. ADDR0, ADDR1 connections select one of sixteen I<sup>2</sup>C slave addresses. Shutdown mode is directly controlled through the I<sup>2</sup>C interface, or a hardware shutdown can be asserted through the  $\overline{\text{RESET}}$  pin.

**Table 1. MAX98371 Control Register Map**

REGISTER DESCRIPTION			REGISTER CONTENTS								POR STATE
ADDR	NAME	R/W	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	
<b>INTERRUPTS</b>											
0x01	INTERRUPT STATUS 0	R	—	—	THRMFB_STATUS	—	THRM WRN_STATUS	—	THRM SHDN_STATUS	—	0x00
0x02	INTERRUPT STATUS 1	R	—	ICCOVC_STATUS	LMTRACT_STATUS	INVAL SLOT_STATUS	DHTACT_STATUS	SPK CURNT_STATUS	PVDD OVFL_STATUS	PVDD UVLO_STATUS	0x00
0x03	INTERRUPT STATE 0	R	—	—	THRMFB_END_STATE	THRMFB_BGN_STATE	THRM WRN_END_STATE	THRM WRN_BGN_STATE	THRM SHDN_END_STATE	THRM SHDN_BGN_STATE	0x00
0x04	INTERRUPT STATE 1	R	—	ICCOVC_STATE	LMTRACT_STATE	INVAL SLOT_STATE	DHTACT_STATE	SPK CURNT_STATE	PVDD OVFL_STATE	PVDD UVLO_STATE	0x00
0x05	INTERRUPT FLAG 0	R/W	—	—	THRMFB_END_FLAG	THRMFB_BGN_FLAG	THRM WRN_END_FLAG	THRM WRN_BGN_FLAG	THRM SHDN_END_FLAG	THRM SHDN_BGN_FLAG	0x00